

Low Noise Amplifier with Bypass for LTE

■ GENERAL DESCRIPTION

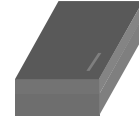
NJG1173UX2 is low noise amplifier with bypass switch for LTE, which covers frequency from 3300MHz to 3800MHz.

NJG1173UX2 is able to select LNA active mode or bypass mode by low control voltage. This LNA achieves low noise figure and high linearity.

Integrated ESD protection device on each port achieves excellent ESD robustness.

A very small and ultra-thin package EPFFP6-X2 is adopted.

■ PACKAGE OUTLINE



NJG1173UX2

■ APPLICATIONS

LTE receive application

WiMAX 3.5GHz receive application

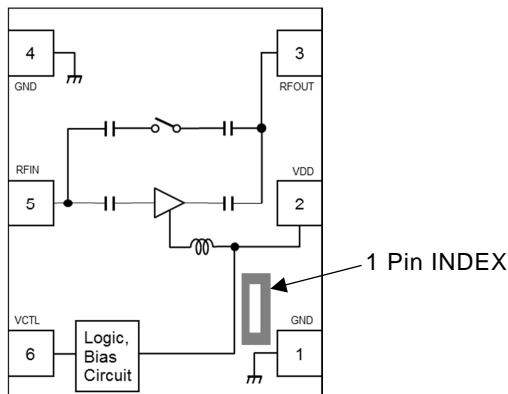
RF front-end modules, smartphones, data cards and others mobile application

■ FEATURES

- Operating frequencies 3300MHz to 3800MHz
- Low control voltage 1.3V to 5.5V
- Low current consumption 5.0/3.5mA typ. @ $V_{DD}=2.8/1.8V$
- High Gain 13.5dB typ. @ $V_{DD}=2.8V$ $f_{RF}=3500MHz$
- Low Noise figure 1.0dB typ. @ $V_{DD}=2.8V$ $f_{RF}=3500MHz$
- High IIP3 +5.0dBm typ. @ $V_{DD}=2.8V$, $f_{RF}=3500MHz+3510MHz$
- Insertion loss in bypass mode 3.5dB typ. @ $V_{DD}=2.8V$, $f_{RF}=3500MHz$
- Ultra-small package size EPFFP6-X2 (1.1mm x 0.7mm x 0.37mm typ.)
- RoHS compliant and Halogen Free, MSL1

■ PIN CONFIGURATION

(Top view)



Pin Connection

1. GND
2. VDD
3. RFOUT
4. GND
5. RFIN
6. VCTL

■ TRUTH TABLE

“H”= $V_{CTL}(H)$, “L”= $V_{CTL}(L)$

| V_{CTL} | Mode |
|-----------|-----------------|
| L | Bypass mode |
| H | LNA active mode |

Note: Specifications and description listed in this datasheet are subject to change without notice

■ ABSOLUTE MAXIMUM RATINGS

General condition: $T_a=+25^{\circ}\text{C}$, $Z_s=Z_l=50\Omega$

| PARAMETER | SYMBOL | CONDITIONS | RATINGS | UNITS |
|-----------------------|-----------|--|-------------|--------------------|
| Operating voltage | V_{DD} | | 6.0 | V |
| Control voltage | V_{CTL} | | 6.0 | V |
| Input power | P_{IN} | $V_{DD}=2.8\text{V}$ | +15 | dBm |
| Power dissipation | P_D | 4-layer FR4 PCB with through-hole (101.5x114.3mm), $T_j=150^{\circ}\text{C}$ | 430 | mW |
| Operating temperature | T_{opr} | | -40 to +105 | $^{\circ}\text{C}$ |
| Storage temperature | T_{stg} | | -55 to +150 | $^{\circ}\text{C}$ |

■ ELECTRICAL CHARACTERISTICS 1 (DC)

General condition: $T_a=+25^{\circ}\text{C}$

| PARAMETERS | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS |
|------------------------|--------------|--|-----|-----|-----|---------------|
| Operating voltage | V_{DD} | | 1.5 | - | 5.5 | V |
| Control voltage (High) | $V_{CTL(H)}$ | | 1.3 | 1.8 | 5.5 | V |
| Control voltage (Low) | $V_{CTL(L)}$ | | 0 | 0 | 0.3 | V |
| Operating current 1 | I_{DD1} | RF OFF, $V_{DD}=2.8\text{V}$, $V_{CTL}=1.8\text{V}$ | - | 5.0 | 8.0 | mA |
| Operating current 2 | I_{DD2} | RF OFF, $V_{DD}=1.8\text{V}$, $V_{CTL}=1.8\text{V}$ | - | 3.5 | 7.0 | mA |
| Operating current 3 | I_{DD3} | RF OFF, $V_{DD}=2.8\text{V}$, $V_{CTL}=0\text{V}$ | - | 15 | 60 | μA |
| Operating current 4 | I_{DD4} | RF OFF, $V_{DD}=1.8\text{V}$, $V_{CTL}=0\text{V}$ | - | 10 | 60 | μA |
| Control current | I_{CTL} | RF OFF, $V_{CTL}=1.8\text{V}$ | - | 7 | 20 | μA |

■ ELECTRICAL CHARACTERISTICS 2 (LNA active mode)

General Condition: $V_{DD}=2.8V$, $V_{CTL}=1.8V$, $f_{RF}=3500MHz$, $T_a=+25^{\circ}C$, $Z_s=Z_l=50\Omega$, with application circuit

| PARAMETERS | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS |
|---|---------------|--|-------|-------|------|---------|
| Small signal gain1 | Gain1 | Exclude PCB & connector losses(0.32dB) | 11.0 | 13.5 | 16.0 | dB |
| Noise figure1 | NF1 | Exclude PCB & connector losses(0.14dB) | - | 1.0 | 1.6 | dB |
| Input power at 1dB gain compression point1(1) | P-1dB(IN)1(1) | | -13.0 | -10.0 | - | dBm |
| Input 3rd order intercept point1(1) | IIP3_1(1) | $f1=f_{RF}$, $f2=f_{RF}+10MHz$, $P_{IN}=-28dBm$ | -2.0 | +5.0 | - | dBm |
| Gain settling time1(1) | Ts1(1) | Bypass to LNA active mode To be within 1 dB of the final gain | - | 1.0 | 2.5 | μs |
| Gain settling time1(2) | Ts1(2) | LNA active to Bypass mode To be within 1 dB of the final insertion loss | - | 0.8 | 2.5 | μs |
| RF IN Return loss1(1) | RLi1(1) | | 5.0 | 9.0 | - | dB |
| RF OUT Return loss1(1) | RLo1(1) | | 10.0 | 15.0 | - | dB |

■ ELECTRICAL CHARACTERISTICS 3 (Bypass mode)

General Condition: $V_{DD}=2.8V$, $V_{CTL}=0V$, $f_{RF}=3500MHz$, $T_a=+25^{\circ}C$, $Z_s=Z_l=50\Omega$, with application circuit

| PARAMETERS | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS |
|--|---------------|---|------|-------|-----|-------|
| Insertion Loss1 | Loss1 | Exclude PCB & connector losses(0.32dB) | - | 3.5 | 5.0 | dB |
| Input power at 1dB Compression point1(2) | P-1dB(IN)1(2) | | -1.0 | +10.0 | - | dBm |
| Input 3rd order intercept point1(2) | IIP3_1(2) | $f1=f_{RF}$, $f2=f_{RF}+10MHz$, $P_{IN}=-10dBm$ | +9.0 | +18.0 | - | dBm |
| RF IN Return loss1(2) | RLi1(2) | | 5.0 | 7.0 | - | dB |
| RF OUT Return loss1(2) | RLo1(2) | | 4.0 | 6.0 | - | dB |

■ ELECTRICAL CHARACTERISTICS 4 (LNA active mode)

General Condition: $V_{DD}=1.8V$, $V_{CTL}=1.8V$, $f_{RF}=3500MHz$, $T_a=+25^{\circ}C$, $Z_s=Z_l=50\Omega$, with application circuit

| PARAMETERS | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS |
|--|----------------------------|--|-----|-------|-----|---------|
| Small signal gain ₂ | Gain ₂ | Exclude PCB & connector losses(0.32dB) | - | 12.0 | - | dB |
| Noise figure ₂ | NF ₂ | Exclude PCB & connector losses(0.14dB) | - | 1.3 | - | dB |
| Input power at 1dB gain compression point ₂ (1) | P-1dB(IN) ₂ (1) | | - | -12.0 | - | dBm |
| Input 3rd order intercept point ₂ (1) | IIP3_2(1) | $f_1=f_{RF}$, $f_2=f_{RF}+10MHz$, $P_{IN}=-28dBm$ | - | 0 | - | dBm |
| Gain settling Time ₂ (1) | Ts ₂ (1) | Bypass to LNA active mode To be within 1 dB of the final gain | - | 2.0 | - | μs |
| Gain settling Time ₂ (2) | Ts ₂ (2) | LNA active to Bypass mode To be within 1 dB of the final insertion loss | - | 0.8 | - | μs |
| RF IN Return loss ₂ (1) | RLi ₂ (1) | | - | 8.0 | - | dB |
| RF OUT Return loss ₂ (1) | RLo ₂ (1) | | - | 15.0 | - | dB |

■ ELECTRICAL CHARACTERISTICS 5 (Bypass mode)

General Condition: $V_{DD}=1.8V$, $V_{CTL}=0V$, $f_{RF}=3500MHz$, $T_a=+25^{\circ}C$, $Z_s=Z_l=50\Omega$, with application circuit

| PARAMETERS | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNITS |
|---|----------------------------|---|-----|-------|-----|-------|
| Insertion Loss ₂ | Loss ₂ | Exclude PCB & connector losses(0.32dB) | - | 3.5 | - | dB |
| Input power at 1dB compression Point ₂ (2) | P-1dB(IN) ₂ (2) | | - | +9.0 | - | dBm |
| Input 3rd order intercept point ₂ (2) | IIP3_2(2) | $f_1=f_{RF}$, $f_2=f_{RF}+10MHz$, $P_{IN}=-10dBm$ | - | +17.0 | - | dBm |
| RF IN Return loss ₂ (2) | RLi ₂ (2) | | - | 7.0 | - | dB |
| RF OUT Return loss ₂ (2) | RLo ₂ (2) | | - | 6.0 | - | dB |

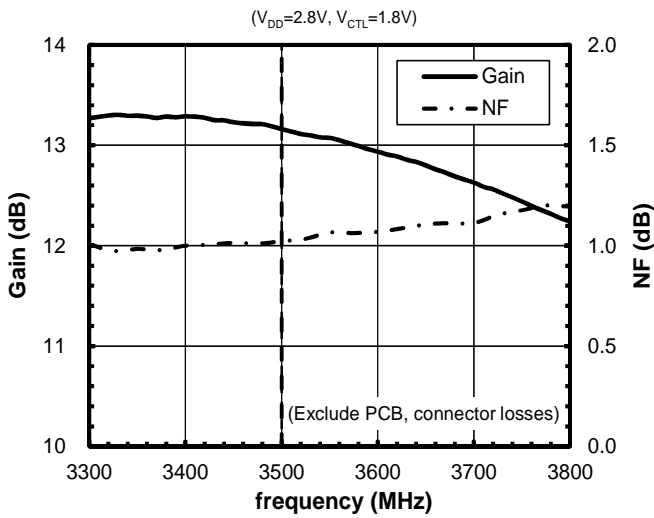
■ TERMINAL INFORMATION

| No. | SYMBOL | DESCRIPTION |
|-----|--------|---|
| 1 | GND | Ground terminal. This terminal should be connected to the ground plane as close as possible for excellent RF performance. |
| 2 | VDD | Supply voltage terminal. Please connect bypass capacitor C1 with ground as close as possible. |
| 3 | RFOUT | RF output terminal. This terminal requires no DC blocking capacitor since this IC has internal output matching circuit including DC blocking capacitor. |
| 4 | GND | Ground terminal. This terminal should be connected to the ground plane as close as possible for excellent RF performance. |
| 5 | RFIN | RF input terminal. This terminal requires only a matching inductor L1, and does not require DC blocking capacitor. |
| 6 | VCTL | Control voltage terminal. |

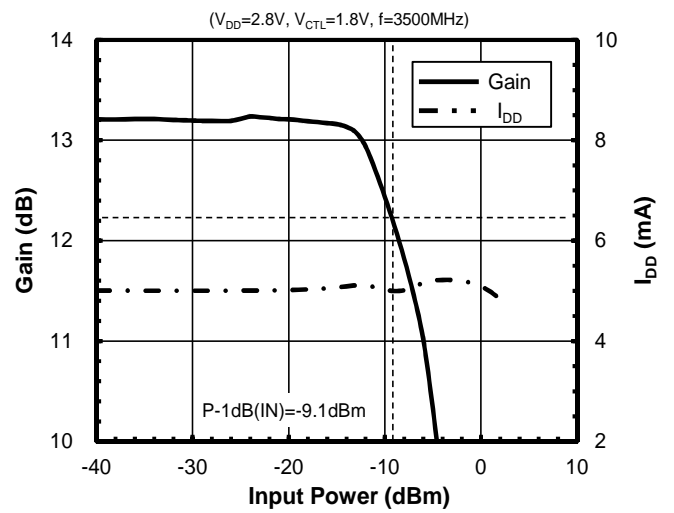
■ ELECTRICAL CHARACTERISTICS (LNA active mode)

Conditions: $V_{DD}=2.8V$, $V_{CTL}=1.8V$, $f_{RF}=3500MHz$, $T_a=+25^{\circ}C$, $Z_s=Z_l=50\Omega$, with application circuit

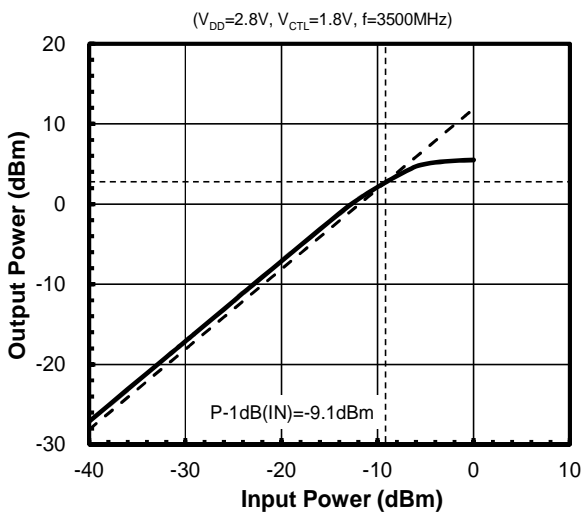
Gain, NF vs. frequency



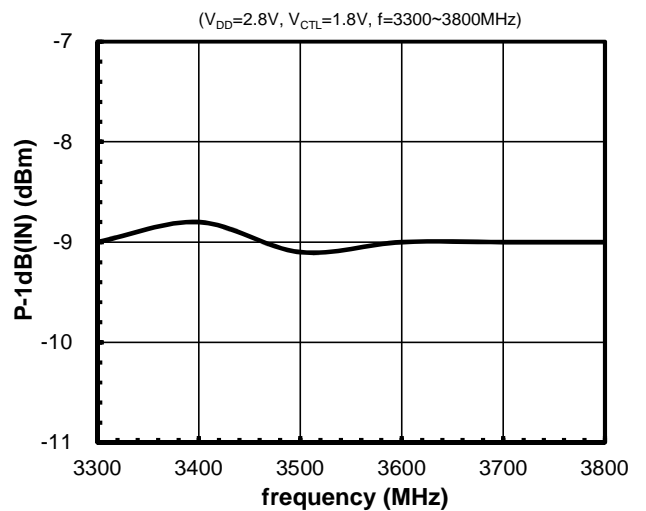
Gain, I_{DD} vs. Pin



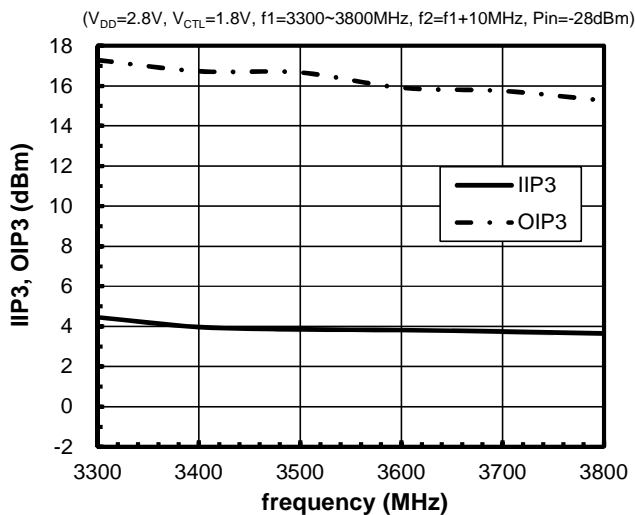
Pout vs. Pin



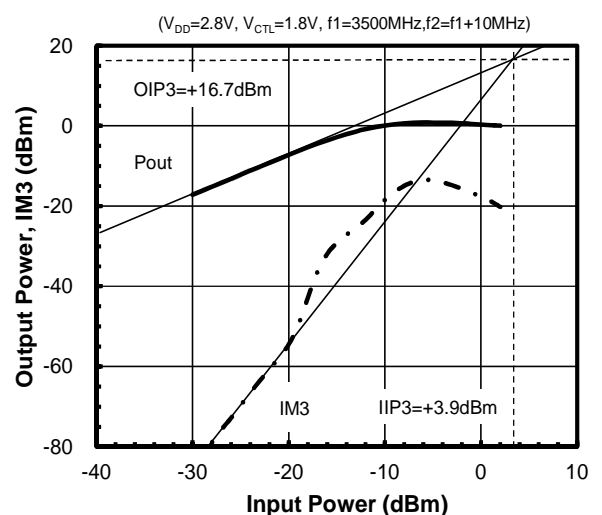
P-1dB(IN) vs. frequency



IIP3, OIP3 vs. frequency

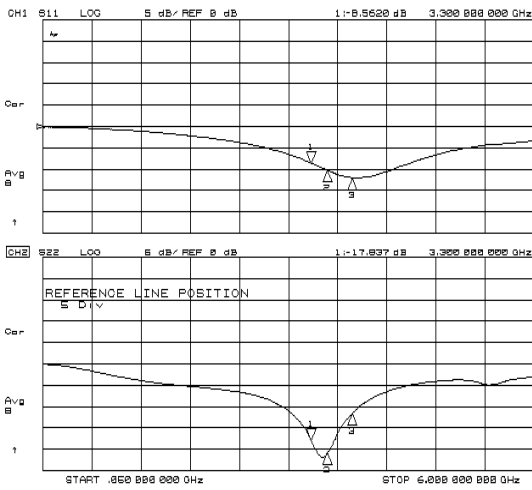


Pout, IM3 vs. Pin

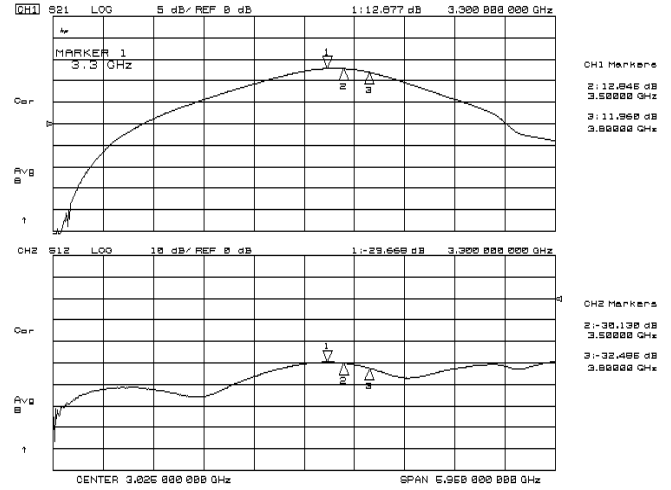


■ ELECTRICAL CHARACTERISTICS (LNA active mode)

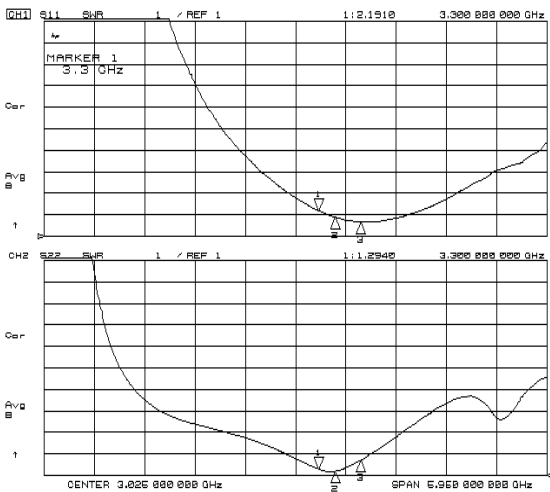
Conditions: $V_{DD}=2.8V$, $V_{CTL}=1.8V$, $f_{RF}=50MHz$ to $6000MHz$, $T_a=+25^{\circ}C$, $Z_s=Z_l=50\Omega$, with application circuit



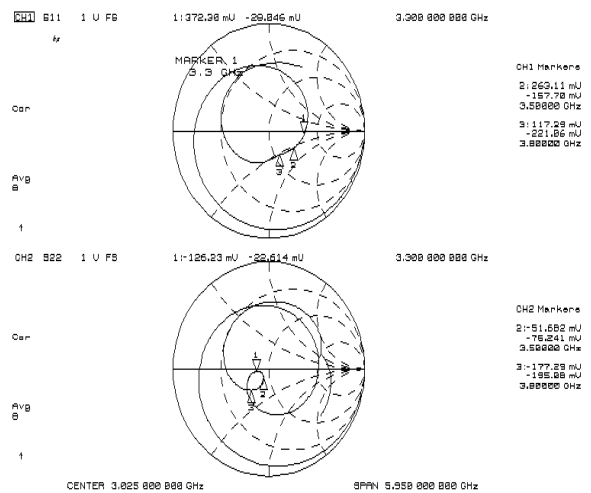
S11, S22



S21, S12



VSWRi, VSWRo



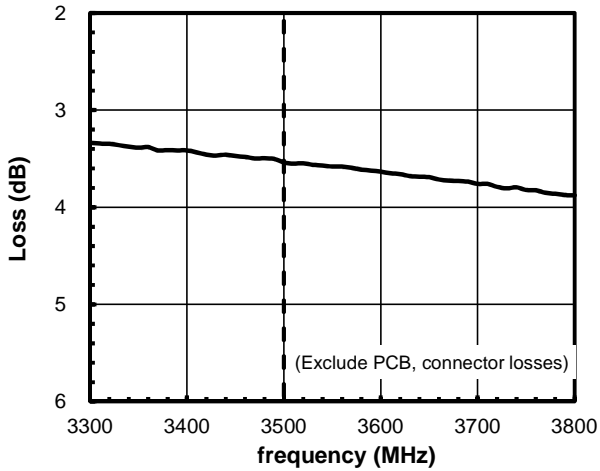
Zin, Zout

■ ELECTRICAL CHARACTERISTICS (Bypass mode)

Conditions: $V_{DD}=2.8V$, $V_{CTL}=0V$, $f_{RF}=3500MHz$, $T_a=+25^{\circ}C$, $Z_s=Z_l=50\Omega$, with application circuit

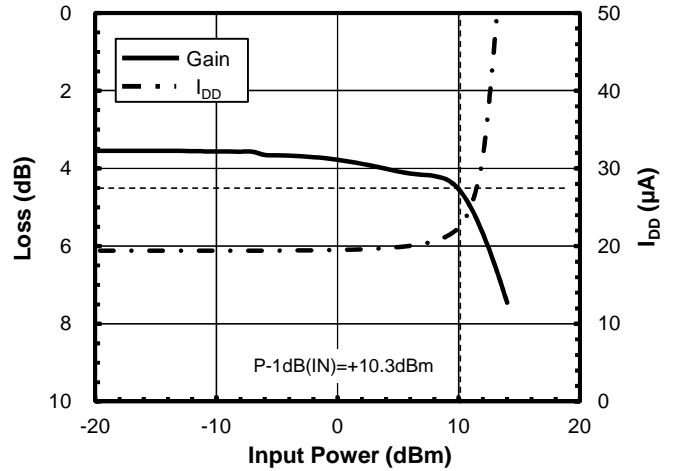
Loss vs. frequency

($V_{DD}=2.8V$, $V_{CTL}=0V$)



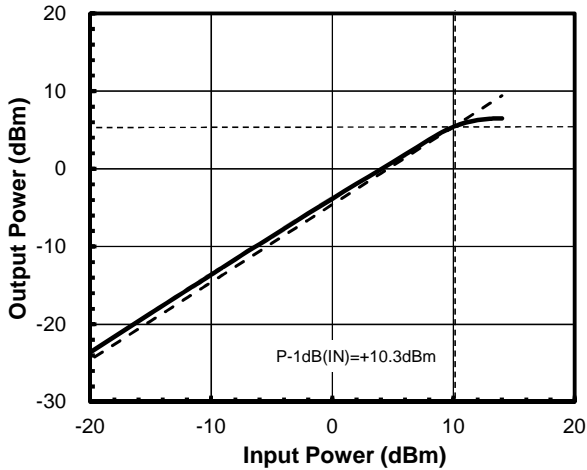
Loss, I_{DD} vs. Pin

($V_{DD}=2.8V$, $V_{CTL}=0V$, $f=3500MHz$)



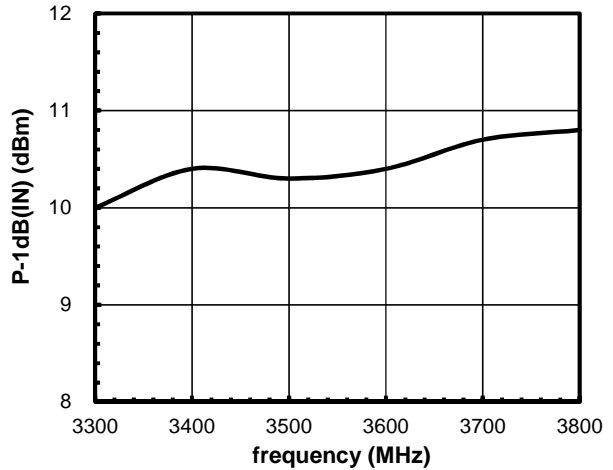
Pout vs. Pin

($V_{DD}=2.8V$, $V_{CTL}=0V$, $f=3500MHz$)



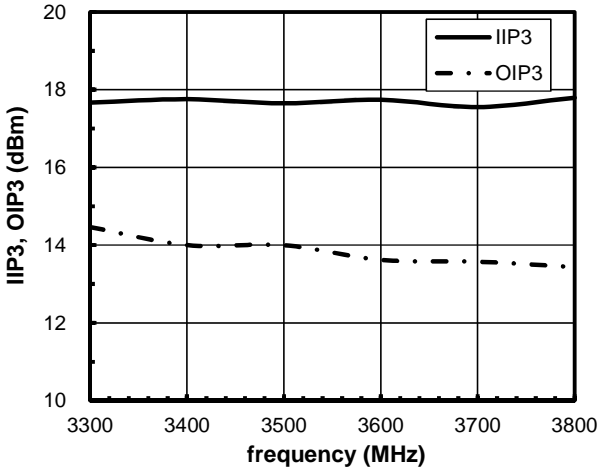
P-1dB(IN) vs. frequency

($V_{DD}=2.8V$, $V_{CTL}=0V$, $f=3300\sim 3800MHz$)



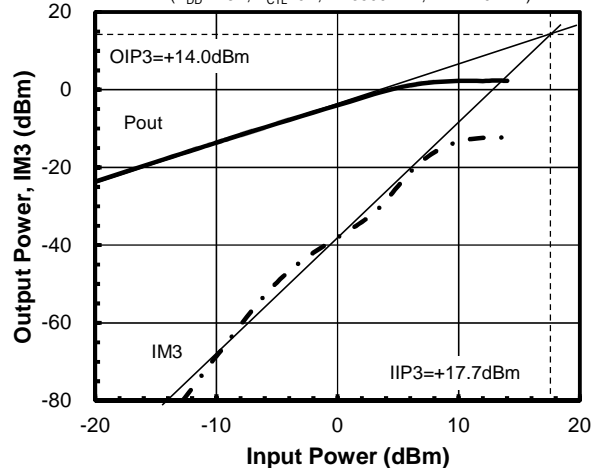
IIP3, OIP3 vs. frequency

($V_{DD}=2.8V$, $V_{CTL}=0V$, $f_1=3300\sim 3800MHz$, $f_2=f_1+10MHz$, $Pin=-10dBm$)



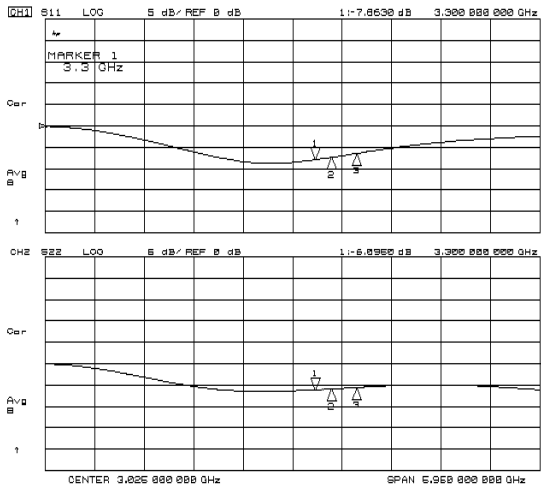
Pout, IM3 vs. Pin

($V_{DD}=2.8V$, $V_{CTL}=0V$, $f_1=3500MHz$, $f_2=f_1+10MHz$)

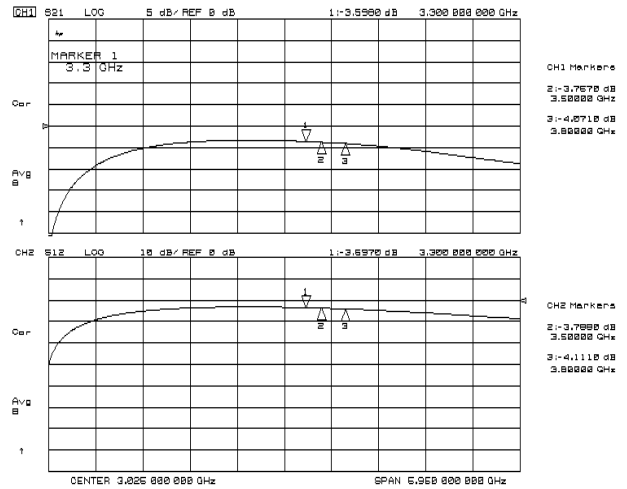


ELECTRICAL CHARACTERISTICS (Bypass mode)

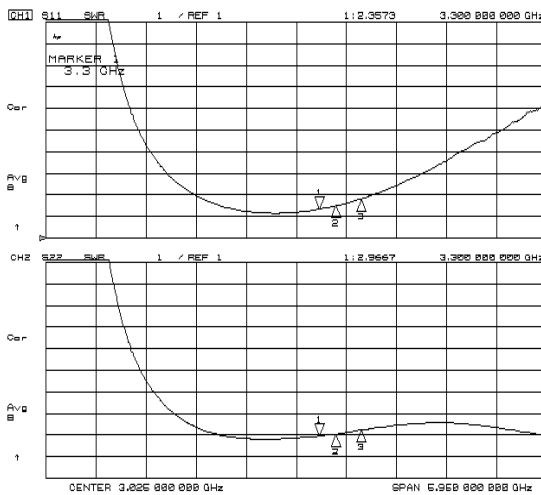
Conditions: $V_{DD}=2.8V$, $V_{CTL}=0V$, $f_{RF}=50MHz$ to $6000MHz$, $T_a=+25^\circ C$, $Z_s=Z_l=50\Omega$, with application circuit



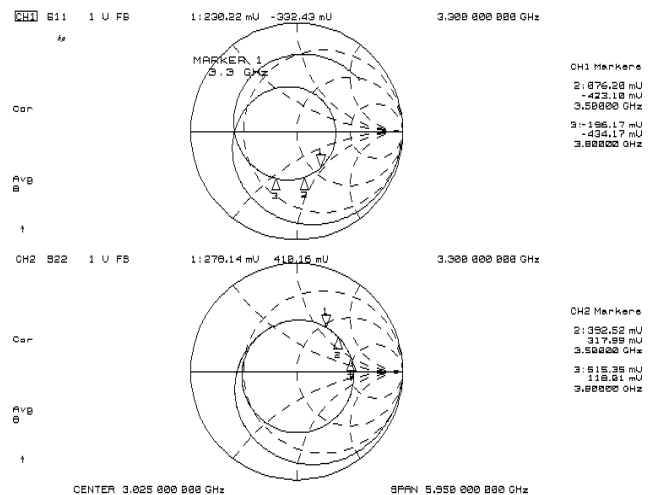
S11, S22



S21, S12



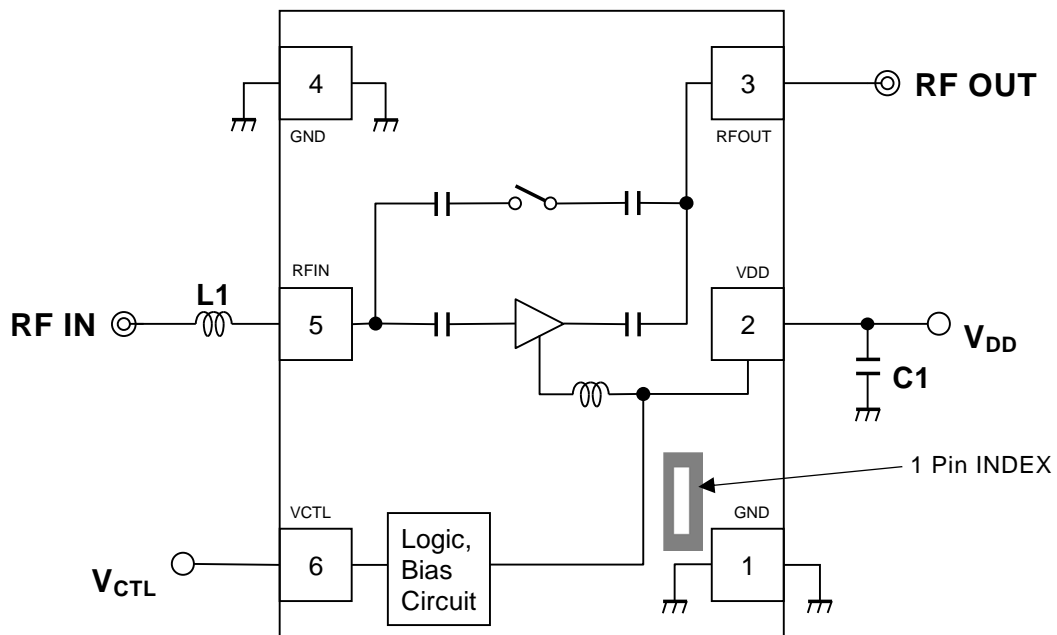
VSWRi, VSWRo



Zin, Zout

APPLICATION CIRCUIT

(TOP VIEW)



Parts list

| Parts ID | Value | Manufacture |
|----------|--------|----------------------------|
| L1 | 2.9nH | LQW15AN_00 Series (MURATA) |
| C1 | 1000pF | GRM03 Series (MURATA) |

■ MEASUREMENT BLOCK DIAGRAM

Measuring instruments

NF Analyzer : Keysight N8975A
 Noise Source : Keysight 346A

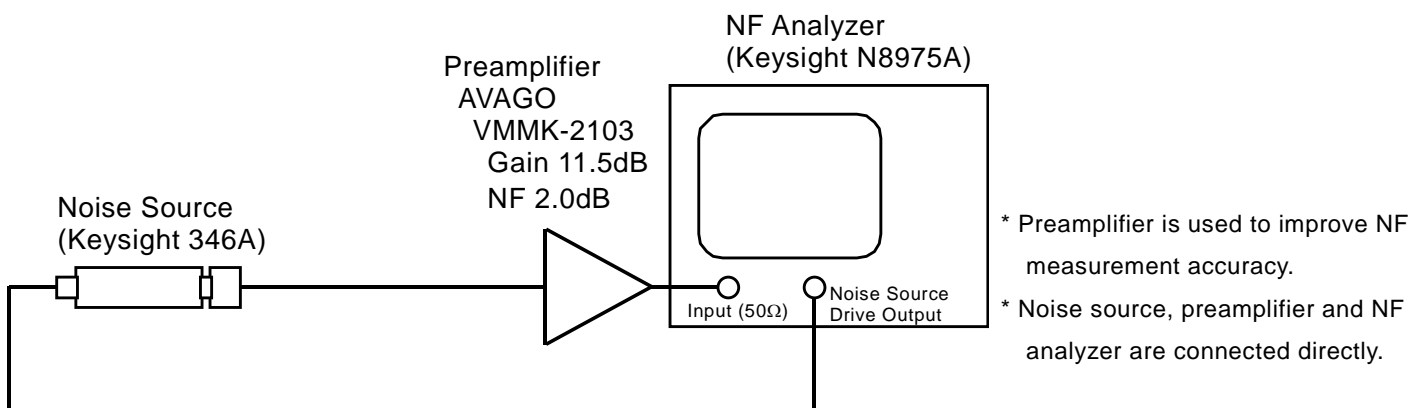
Setting the NF analyzer

Measurement mode form

Device under test : Amplifier
 System downconverter : off

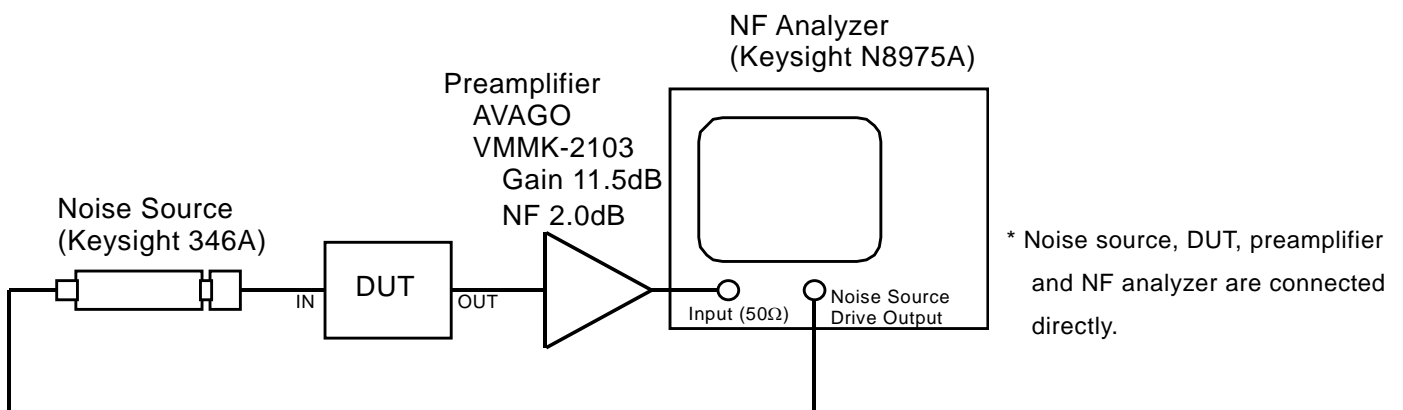
Mode setup form

Sideband : LSB
 Averages : 16
 Average mode : Point
 Bandwidth : 4MHz
 Loss comp : off
 Tcold : setting the temperature of noise source (305.15K)



* Pre-amplifier is used to improve NF measurement accuracy.
 * Noise source, pre-amplifier and NF analyzer are connected directly.

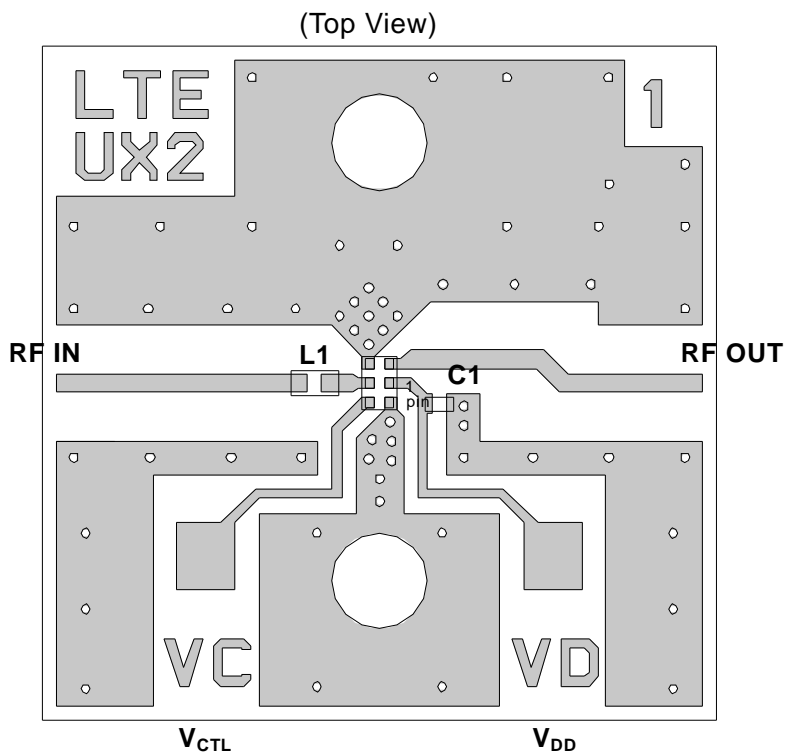
Calibration setup



* Noise source, DUT, pre-amplifier and NF analyzer are connected directly.

Measurement Setup

■ EVALUATION BOARD



PCB Information

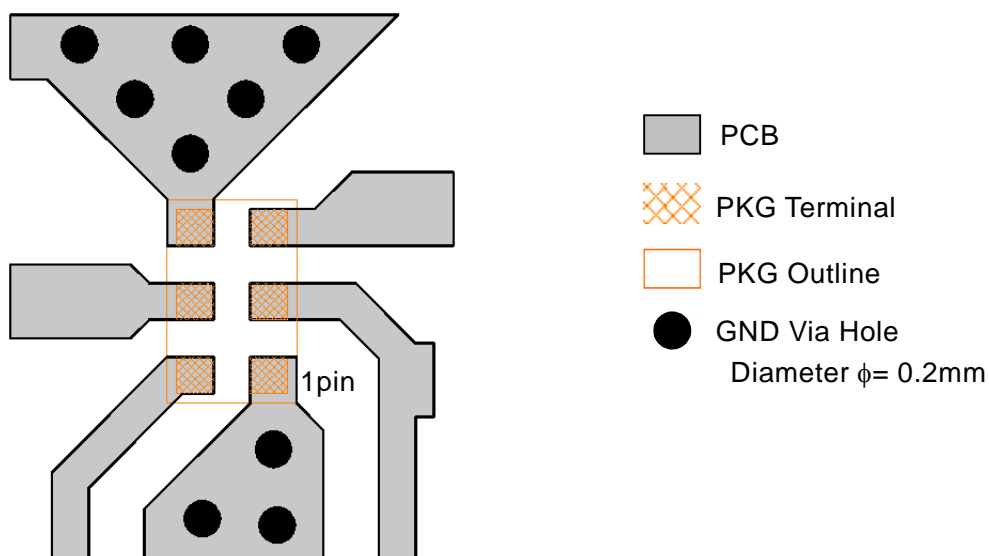
Substrate: FR-4

Thickness: 0.2mm

Microstrip line width: 0.4mm ($Z_0=50\Omega$)

Size: 14.0mm x 14.0mm

< PCB LAYOUT GUIDELINE >




PRECAUTIONS

- All external parts should be placed as close as possible to the IC.
- For good RF performance, all GND terminals must be connected to PCB ground plane of substrate, and via-holes for GND should be placed near the IC.


RECOMMENDED FOOTPRINT PATTERN (EPFFP6-X2 PACKAGE)

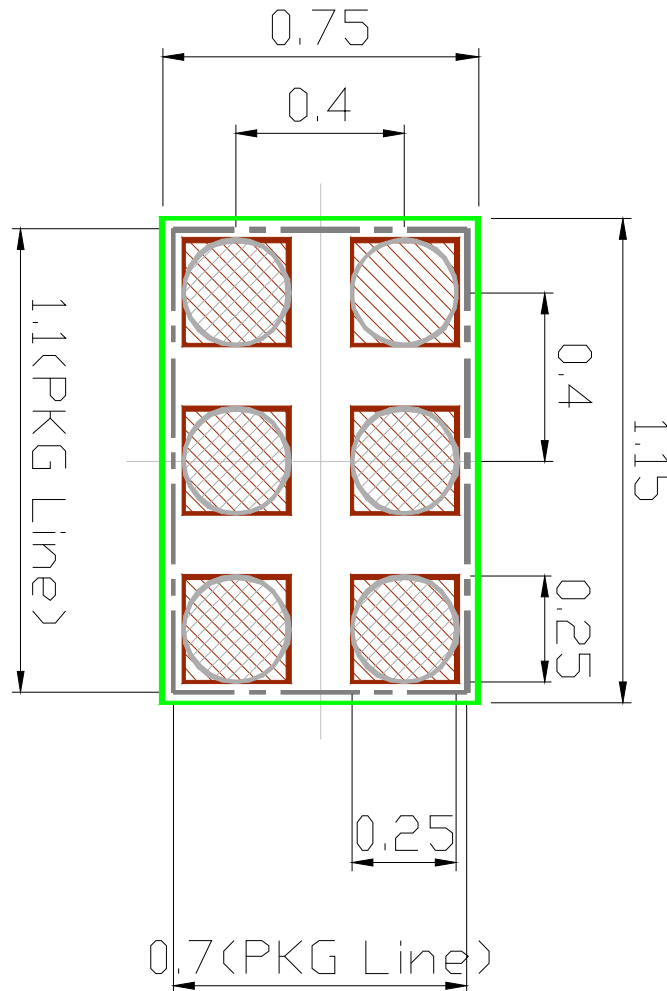
Package: 1.1mm x 0.7mm

Pin pitch: 0.4mm

 : Land

 : Mask (Open area) *Metal mask thickness: 100μm

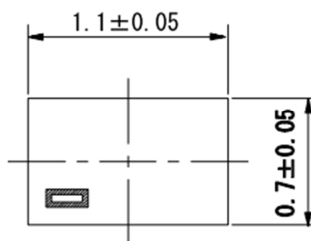
 : Resist (Open area)



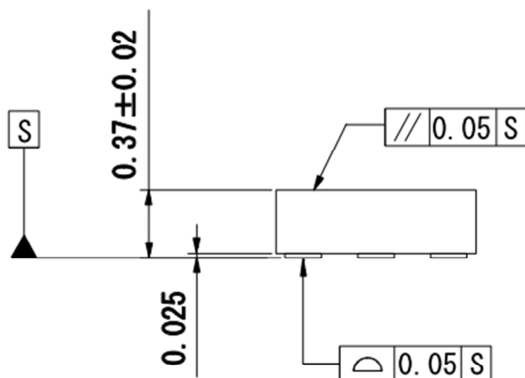
Unit : mm

PACKAGE OUTLINE (EPFFP6-X2)

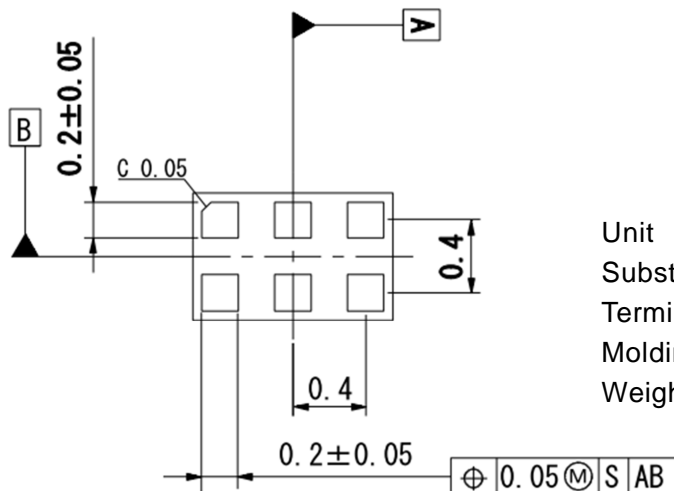
TOP VIEW



SIDE VIEW



BOTTOM VIEW



Unit : mm
 Substrate : FR4
 Terminal treat : Ni/Pd/Au
 Molding material : Epoxy resin
 Weight (typ.) : 0.7mg

Cautions on using this product

This product contains Gallium-Arsenide (GaAs) which is a harmful material.

- Do NOT eat or put into mouth.
- Do NOT dispose in fire or break up this product.
- Do NOT chemically make gas or powder with this product.
- To waste this product, please obey the relating law of your country.

This product may be damaged with electric static discharge (ESD) or spike voltage. Please handle with care to avoid these damages.

[CAUTION]

The specifications on this databook are only given for information, without any guarantee as regards either mistakes or omissions.

The application circuits in this databook are described only to show representative usages of the product and not intended for the guarantee or permission of any right including the industrial rights.

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Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.